ABSTRACT OF THE DISCLOSURE

LEAD FRAME FOR LEAD ON CHIP

A lead frame for LOC to which a semiconductor chip is fixed within a semiconductor chip-mounting region. In addition to applying insulative adhesives to the conventional portions or spots which are on the bottom surfaces of the leading edges of respective inner leads for wire bonding to the pads for the semiconductor ship, the insulative adhesives are applied to other portions of the inner leads in the vicinity of the semiconductor chip-mounting region. Accordingly, the area for bonding the semiconductor chip can be enlarged resulting in improvements in the stability of adhesion between the leads and the semiconductor chip, and in the stabilities of wire bonding and resin molding.

(Figure 2)